



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

KONISHI et al.

Atty. Ref.: 829-615; Confirmation No.

Appl. No. 10/659,261

TC/A.U. 1722

Filed: September 11, 2003

Examiner: Davis, Robert B.

For: RESIN MOLDING DIE AND PRODUCTION METHOD FOR SEMICONDUCTOR
DEVICES USING THE SAME

* * * * *

August 30, 2005

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

AMENDMENT

Responsive to the Official Action dated May 4, 2005 (for which petition is hereby made
for a one month extension of time), please amend the above-identified application as follows:

08/31/2005 JADD01 00000141 10659261

01 FC:1251

120.00 OP